

Specification of Thermoelectric Module

TEHC1-04904S

Description

The 49 couples, 45 mm × 15 mm size single module which is made of selected high performance ingot to achieve superior cooling performance and greater delta T up to 74, designed for superior cooling and heating up to 100 °C applications. If higher operation or processing temperature is required, please specify, we can design and manufacture the custom made module according to your special requirements.

Features

- No moving parts, no noise, and solid-state
- Compact structure, small in size, light in weight
- Environmental friendly
- RoHS compliant
- Precise temperature control
- Exceptionally reliable in quality, high performance

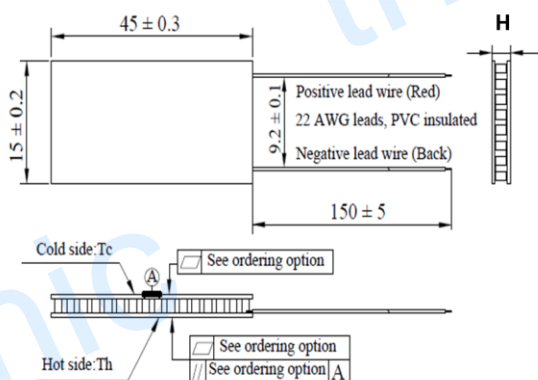
Application

- Food and beverage service refrigerator
- Portable cooler box for cars
- Liquid cooling
- Temperature stabilizer
- CPU cooler and scientific instrument
- Photonic and medical systems

Performance Specification Sheet

Th (°C)	27	50	Hot side temperature at environment: dry air, N ₂
DT _{max} (°C)	74	83	Temperature Difference between cold and hot side of the module when cooling capacity is zero at cold side
U _{max} (Voltage)	6.5	7.0	Voltage applied to the module at DT _{max}
I _{max} (amps)	4.6	4.6	DC current through the modules at DT _{max}
Q _{Cmax} (Watts)	18.5	19.9	Cooling capacity at cold side of the module under DT=0 °C
AC resistance (ohms)	1.1	1.2	The module resistance is tested under AC
Tolerance (%)	± 10		For thermal and electricity parameters

Geometric Characteristics Dimensions in millimeters



Sealing Option

A. Solder:

1. T100: BiSn (Melting Point=138°C)
2. T200: CuSn (Melting Point= 227 °C)

B. Sealant:

1. NS: No sealing (Standard)
2. SS: Silicone sealant
3. EPS: Epoxy sealant
4. Customer specify sealing

C. Ceramics:

1. Alumina (Al₂O₃, white 96%)(AIO)
2. Aluminum Nitride (AlN)

D. Ceramics Surface Options:

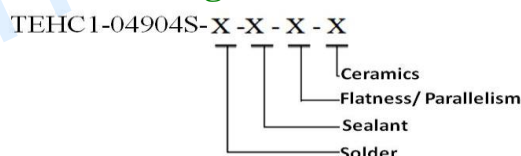
1. Blank ceramics (not metalized)
2. Metalized (Copper-Nickel plating)

Ordering Option

Suffix	Thickness (mm)	Flatness/ Parallelism (mm)	Lead wire length(mm) Standard/Optional length
TF	0:5.0±0.1	0:0.13/0.15	150±5/Specify
TF	1:5.0±0.05	1:0.1/0.13	150±5/Specify
TF	2:5.0±0.025	2:0.08/0.1	150±5/Specify

Eg. TF01: Thickness 5.0 ± 0.1(mm) and Flatness 0.1/0.13 (mm)

Naming for the Module



TEHC1-04904S-T100-NS-TF01-AIO

T100: BiSn (Tmelt=138°C)

NS: No sealing

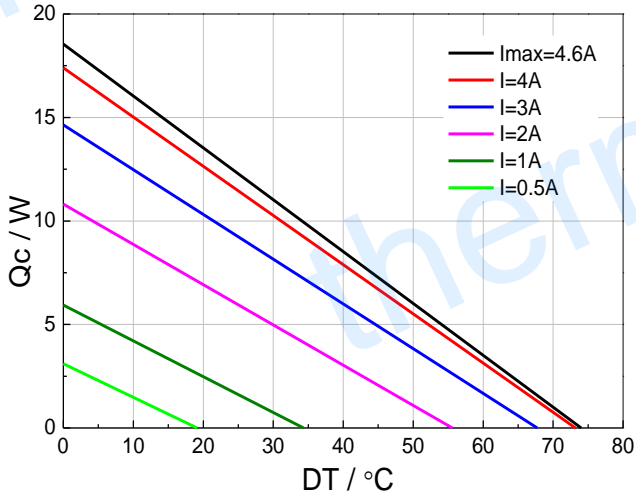
AIO: Alumina(Al₂O₃, white 96%)

TF01: Thickness ± 0.1(mm) and Flatness/Parallelism: 0.1/0.13 (mm)

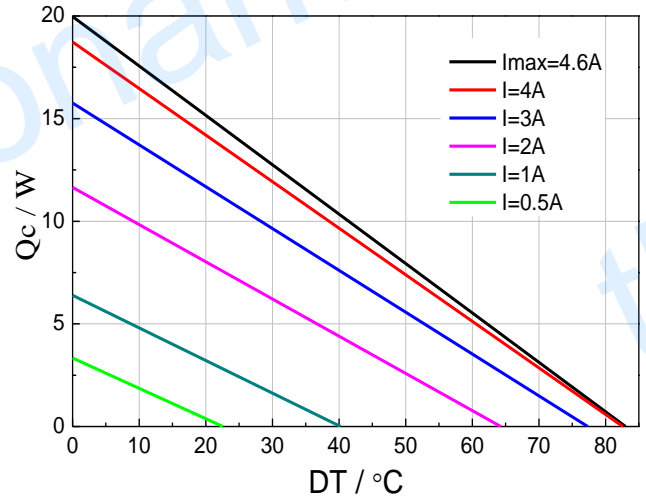
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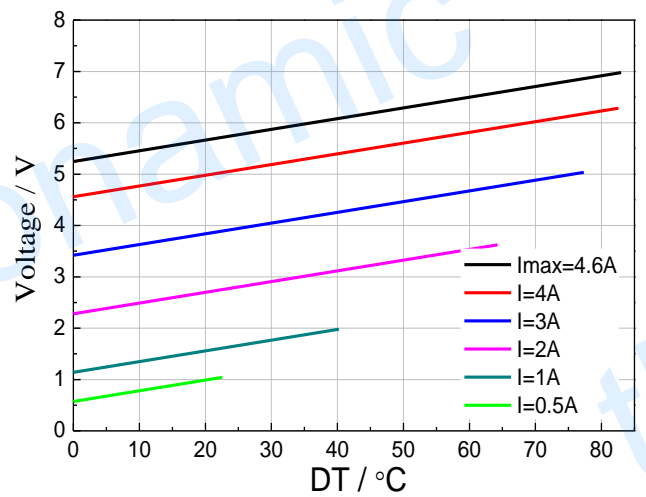
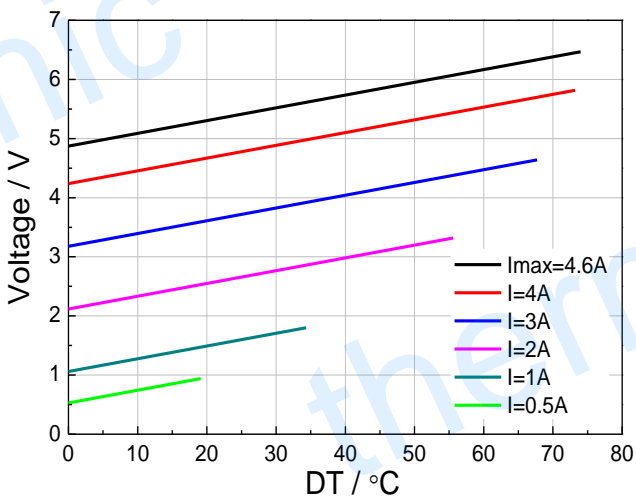
Performance Curves at Th=27 °C



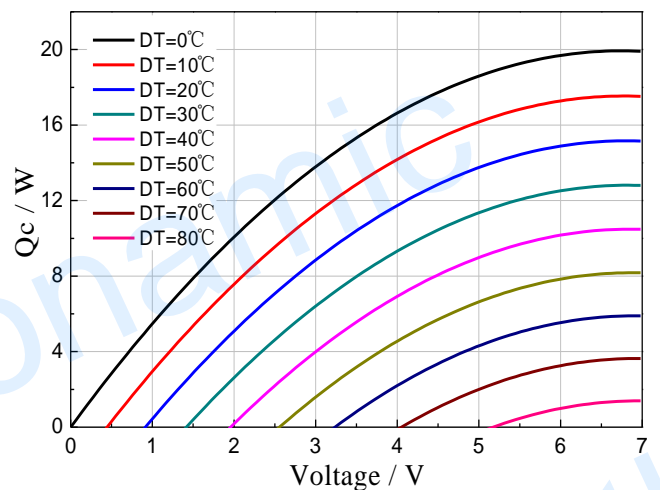
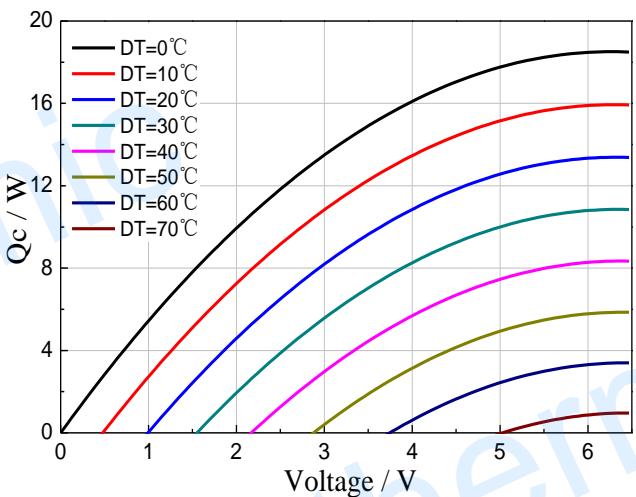
Performance Curves at Th=50 °C



Standard Performance Graph $Q_c = f(DT)$



Standard Performance Graph $V = f(\Delta T)$

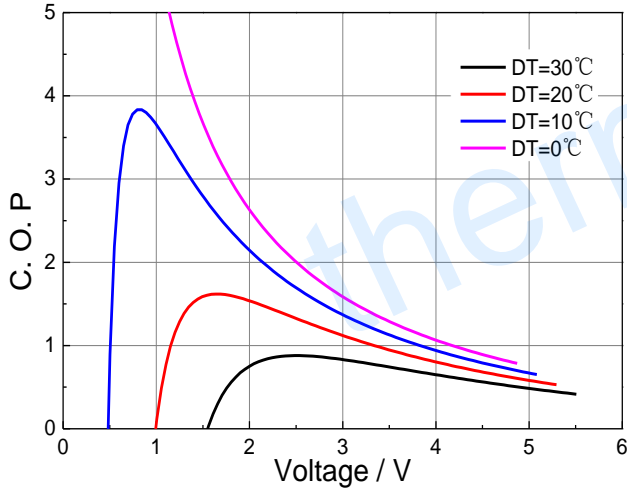


Standard Performance Graph $Q_c = f(V)$

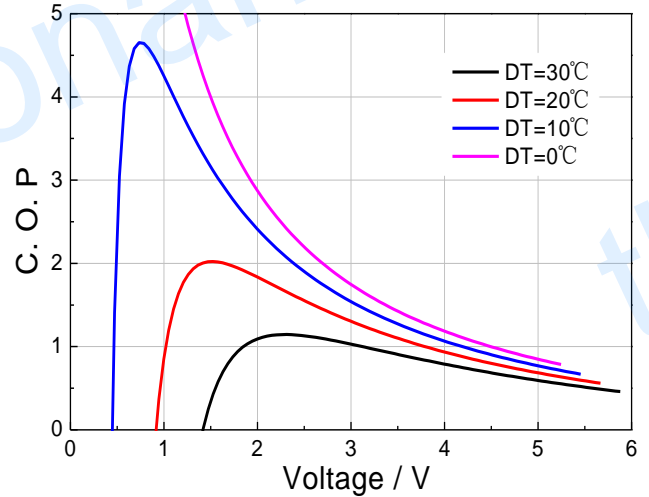
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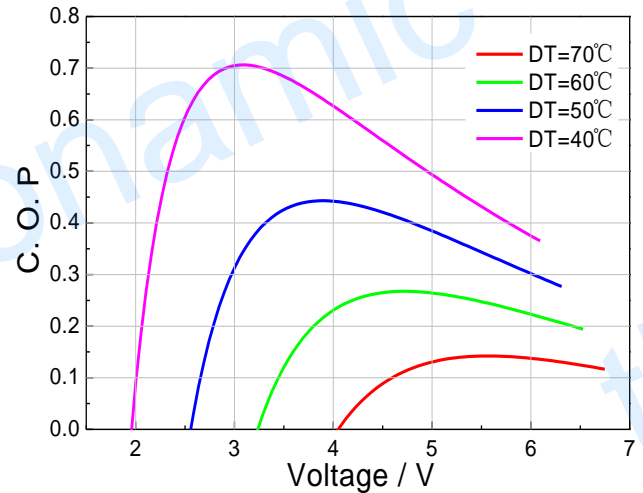
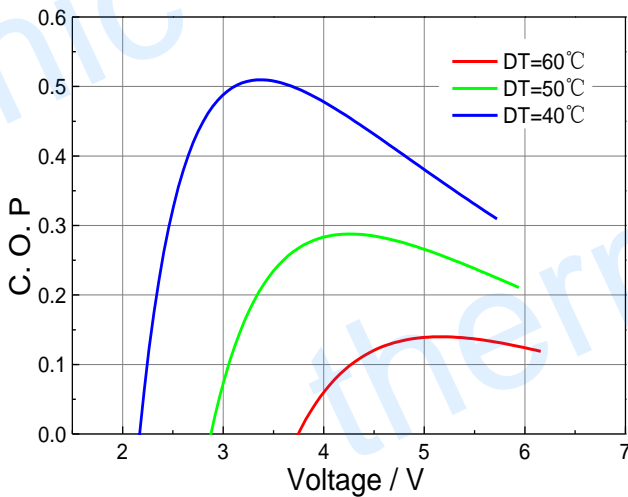
Performance Curves at Th=27 °C



Performance Curves at Th=50 °C



Standard Performance Graph COP = f(V) of ΔT ranged from 0 to 30 °C



Standard Performance Graph COP = f(V) of ΔT ranged from 40 to 60/70 °C

Remark: The coefficient of performance (COP) is the cooling power Q_c /Input power ($V \times I$).

Operation Cautions

- Cold side of the module stucked on the object being cooled
- Hot side of the module mounted on a heat radiator
- Operation or storage module below 100 °C
- Operation below I_{max} or V_{max}
- Work under DC